



Press release
Irvine, California, July 10, 2006

Pb-free Compatible Stacked Package Die Attach Adhesive Now Available from Henkel

While technical capability is certainly the top criteria in selecting advanced materials for next-generation packaging applications, semiconductor specialists also place equal importance on supply chain simplicity and manufacturing efficiency. With this in mind, Henkel has once again developed a superior packaging material to meet the emerging requirements of leading semiconductor firms.

Developed specifically for stacked die applications that require extremely low stress and robust mechanical properties, the electronics group of Henkel has introduced Hysol® QMI536NB. Unlike other die attach materials used for stacked die manufacture, Hysol QMI536NB can be used on all levels of a stacked die, enabling packaging specialists to qualify a single material. This one-material capability provides significant supply chain efficiency and reduces overall manufacturing costs.

“Daughter die generally need a filler that won’t damage the die passivation of the mother die, but use of these fillers often tends to increase resin bleed,” comments Michael Buckley, Henkel Global Product Manager for Die Attach Materials. “Hysol QMI536NB eliminates these issues, delivering very low bleed and allowing use of a single material for all layers of a stacked die.”

Hysol QMI536NB is a non-conductive PTFE-filled paste that exhibits low resin bleed and has very fast cure capability. Enhanced reliability of the material is ensured even on a wide variety of surfaces, including solder resist, bare silicon and multiple die passivations, which gives packaging specialists amazing process flexibility.

In addition to all of these benefits, Hysol QMI536NB is also lead-free compatible, showing no reliability issues or material deterioration even when processed in higher temperature lead-free environments. Extensive testing after multiple exposures to 260°C+ reflow temperatures shows Hysol QMI536NB’s high resistance to delamination and popcorning, making this material ideal for packaging firms wishing to qualify a robust material suitable for the most demanding production environments.

Adhesin

Bonderite

Hysol



LOCTITE



technomelt



For more information on Hysol QMI536NB or any of Henkel's advanced die attach materials, log onto www.electronics.henkel.com or call the company's Irvine, California headquarters at 949-789-2500.

About the electronics group of Henkel

Henkel is one of the world's leading and most progressive providers of qualified, compatible material sets for semiconductor packaging, board level assembly and advanced soldering solutions. Through its Hysol, Loctite and Multicore brands, and its global customer support infrastructure, the electronics group of Henkel delivers world-class materials products, process expertise and total solutions across the board to enable tomorrow's electronic industry.

Henkel, a Fortune Global 500 company, operates in three strategic business areas: Home Care; Personal care; and Adhesives, Sealants and Surface Treatments, which serves the transportation, electronics, aerospace, metal, durable goods, consumer goods, maintenance and repair and packaging industries, and offers a broad range of products for the craftsman and consumer. With brands and technologies, Henkel makes people's lives easier, better, and more beautiful. 50,000 employees work for Henkel worldwide. People in 125 countries around the world trust in brands and technologies from Henkel – "A Brand like a Friend".

Contact

Henkel Corporation

doug.dixon@us.henkel.com

Doug Dixon

www.electronics.henkel.com

Phone: 949-789-2500

Fax: 949-785-2595